



November 2014

# FDBL0630N150

## N-Channel Power Trench<sup>®</sup> MOSFET

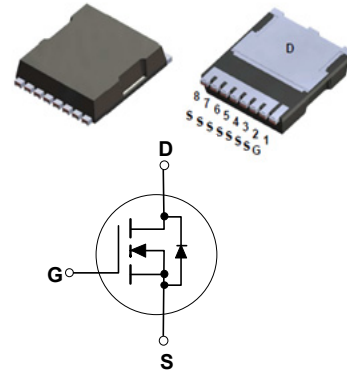
### 150V, 169A, 6.3mΩ

#### Features

- Typ  $r_{DS(on)}$  = 5mΩ at  $V_{GS} = 10V$ ,  $I_D = 80A$
- Typ  $Q_{g(tot)}$  = 70nC at  $V_{GS} = 10V$ ,  $I_D = 80A$
- UIS Capability
- RoHS Compliant

#### Applications

- Industrial Motor Drive
- Industrial Power Supply
- Industrial Automation
- Battery Operated tools
- Battery Protection
- Solar Inverters
- UPS and Energy Inverters
- Energy Storage
- Load Switch



For current package drawing, please refer to the Fairchild website at [https://www.fairchildsemi.com/evaluate/package-specifications/packageDetails.html?id=PN\\_PSOFA-008](https://www.fairchildsemi.com/evaluate/package-specifications/packageDetails.html?id=PN_PSOFA-008)

#### MOSFET Maximum Ratings $T_J = 25^\circ C$ unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DSS}$	Drain to Source Voltage	150	V
$V_{GS}$	Gate to Source Voltage	±20	V
$I_D$	Drain Current - Continuous ( $V_{GS}=10$ ) (Note 1)	$T_C = 25^\circ C$	169
	Pulsed Drain Current	$T_C = 25^\circ C$	See Figure4
$E_{AS}$	Single Pulse Avalanche Energy (Note 2)	502	mJ
$P_D$	Power Dissipation	500	W
	Derate above $25^\circ C$	3.3	W/ $^\circ C$
$T_J, T_{STG}$	Operating and Storage Temperature	-55 to + 175	$^\circ C$
$R_{\theta JC}$	Thermal Resistance Junction to Case	0.3	$^\circ C/W$
$R_{\theta JA}$	Maximum Thermal Resistance Junction to Ambient (Note 3)	43	$^\circ C/W$

#### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDBL0630N150	FDBL0630N150	MO-299A	-	-	-

#### Notes:

- 1: Current is limited by junction temperature.
- 2: Starting  $T_J = 25^\circ C$ ,  $L = 0.24mH$ ,  $I_{AS} = 64A$ ,  $V_{DD} = 100V$  during inductor charging and  $V_{DD} = 0V$  during time in avalanche
- 3:  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta JA}$  is determined by the user's board design. The maximum rating presented here is based on mounting on a 1 in<sup>2</sup> pad of 2oz copper.

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**Electrical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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**Off Characteristics**

$B_{VDSS}$	Drain to Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	150	-	-	V
$I_{DSS}$	Drain to Source Leakage Current	$V_{DS} = 150\text{V}, T_J = 25^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$V_{GS} = 0\text{V}, T_J = 175^\circ\text{C}(\text{Note 4})$	-	-	1	mA
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA

**On Characteristics**

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	2.0	2.8	4.0	V
$r_{DS(on)}$	Drain to Source On Resistance	$I_D = 80\text{A}, T_J = 25^\circ\text{C}$	-	5	6.3	$\text{m}\Omega$
		$V_{GS} = 10\text{V}, T_J = 175^\circ\text{C}(\text{Note 4})$	-	14	17.5	$\text{m}\Omega$

**Dynamic Characteristics**

$C_{iss}$	Input Capacitance	$V_{DS} = 75\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	-	5805	-	pF
$C_{oss}$	Output Capacitance		-	536	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	16	-	pF
$R_g$	Gate Resistance	$f = 1\text{MHz}$	-	2.2	-	$\Omega$
$Q_{g(ToT)}$	Total Gate Charge at 10V	$V_{GS} = 0$ to 10V	-	70	90	nC
$Q_{g(th)}$	Threshold Gate Charge	$V_{GS} = 0$ to 2V				
$Q_{gs}$	Gate to Source Gate Charge	$V_{DD} = 75\text{V}, I_D = 80\text{A}$	-	32.5	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge		-	10	-	nC

**Switching Characteristics**

$t_{on}$	Turn-On Time	$V_{DD} = 75\text{V}, I_D = 80\text{A}, V_{GS} = 10\text{V}, R_{GEN} = 6\Omega$	-	-	80	ns
$t_{d(on)}$	Turn-On Delay Time		-	39	-	ns
$t_r$	Rise Time		-	30	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	70	-	ns
$t_f$	Fall Time		-	23	-	ns
$t_{off}$	Turn-Off Time		-	-	130	ns

**Drain-Source Diode Characteristics**

$V_{SD}$	Source to Drain Diode Voltage	$I_{SD} = 80\text{A}, V_{GS} = 0\text{V}$	-	-	1.25	V
		$I_{SD} = 40\text{A}, V_{GS} = 0\text{V}$	-	-	1.2	V
$T_{rr}$	Reverse Recovery Time	$I_F = 80\text{A}, dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	108	125	ns
$Q_{rr}$	Reverse Recovery Charge	$V_{DD} = 120\text{V}$	-	323	467	nC

**Notes:**

 4: The maximum value is specified by design at  $T_J = 175^\circ\text{C}$ . Product is not tested to this condition in production.

### Typical Characteristics

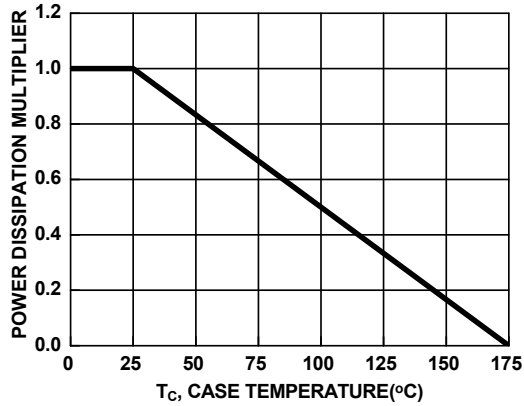


Figure 1. Normalized Power Dissipation vs Case Temperature

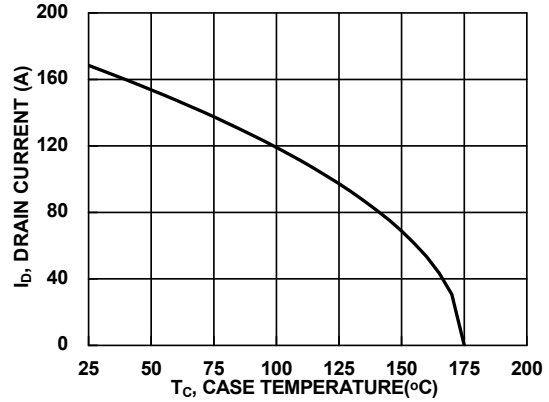


Figure 2. Maximum Continuous Drain Current vs Case Temperature

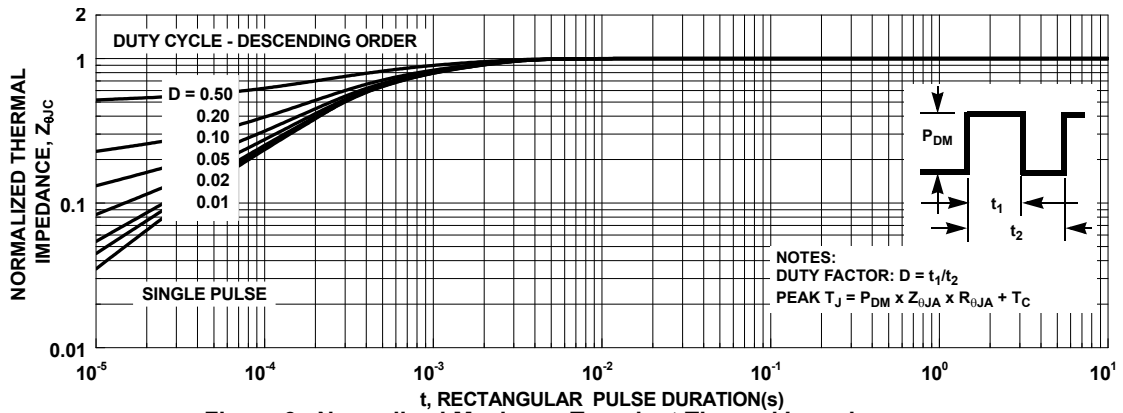


Figure 3. Normalized Maximum Transient Thermal Impedance

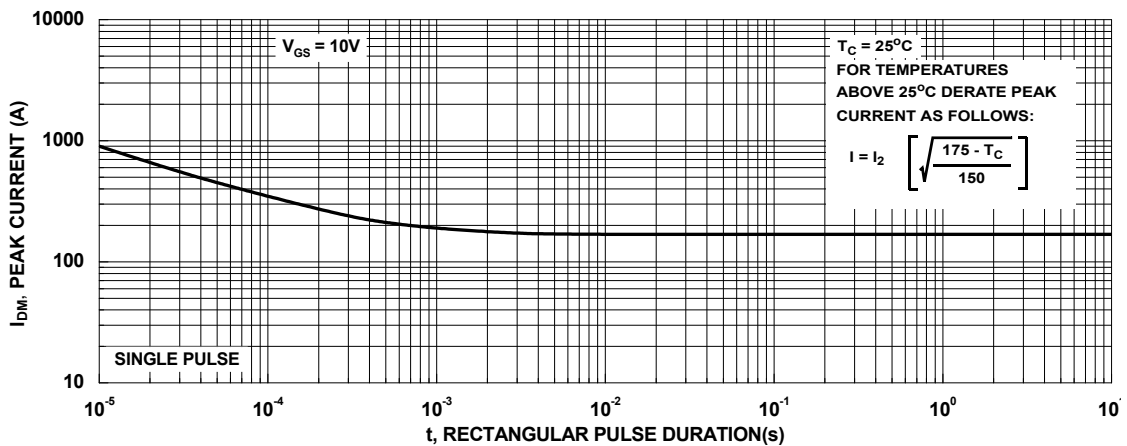


Figure 4. Peak Current Capability

## Typical Characteristics

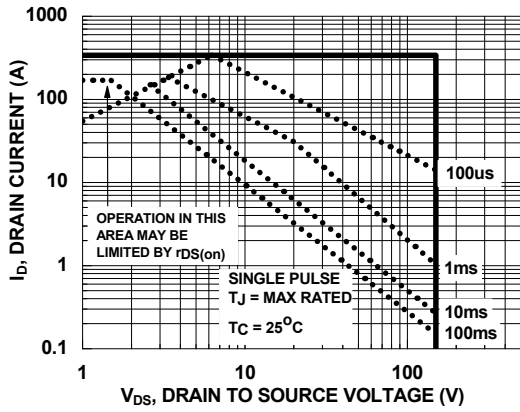
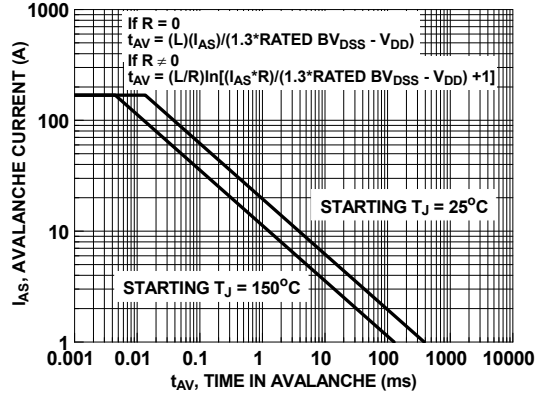


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515  
 Figure 6. Unclamped Inductive Switching Capability

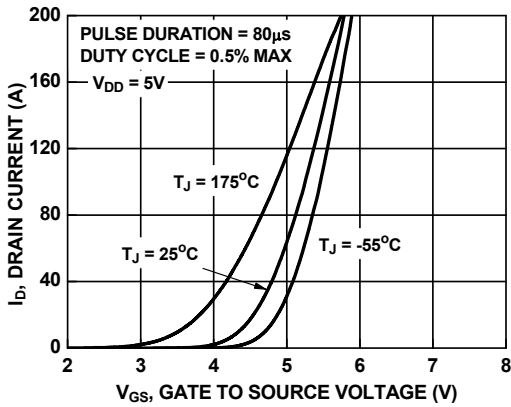


Figure 7. Transfer Characteristics

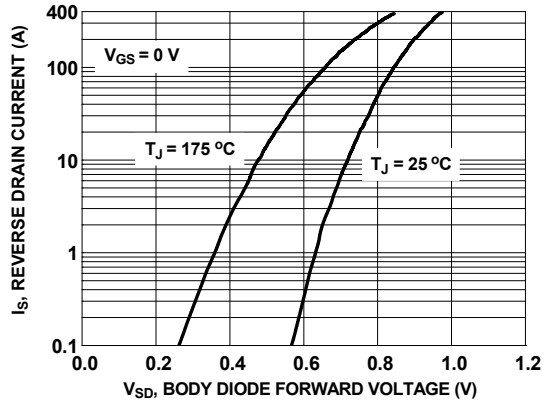


Figure 8. Forward Diode Characteristics

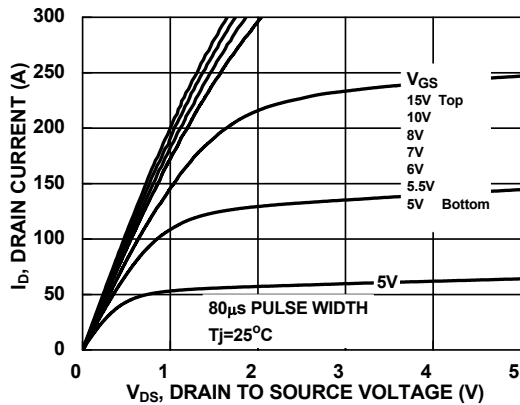


Figure 9. Saturation Characteristics

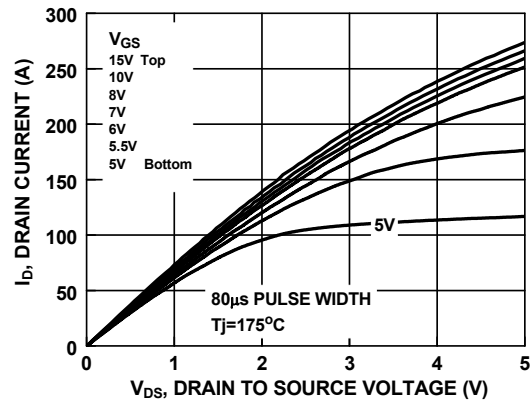


Figure 10. Saturation Characteristics

## Typical Characteristics

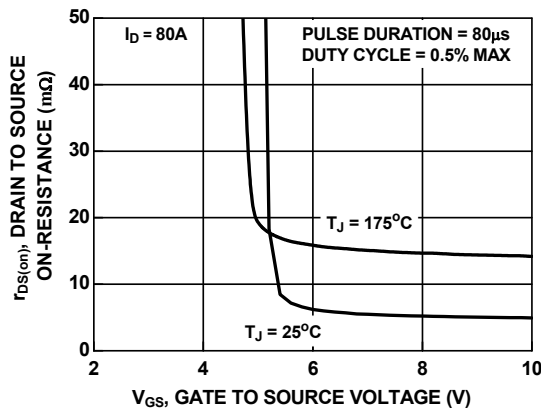


Figure 11. Rdson vs Gate Voltage

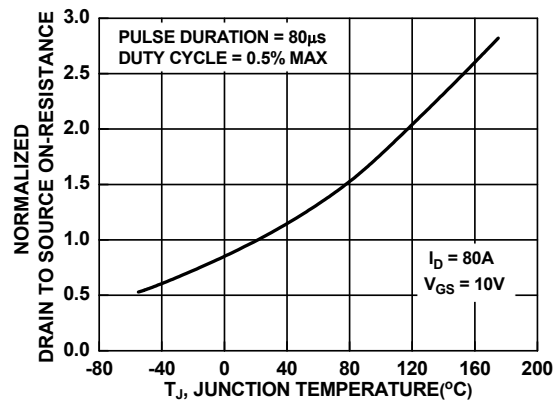


Figure 12. Normalized Rdson vs Junction Temperature

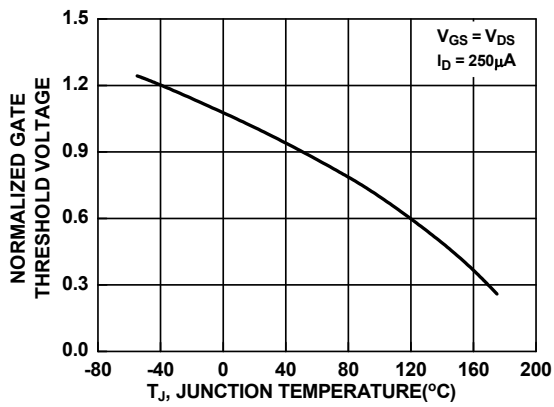


Figure 13. Normalized Gate Threshold Voltage vs Temperature

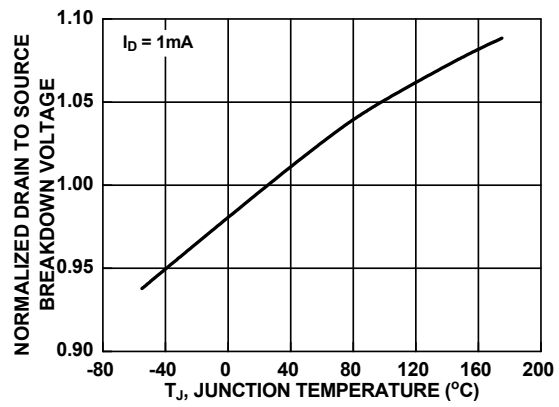


Figure 14. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

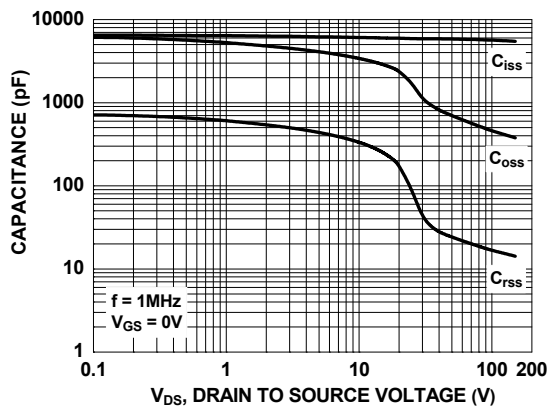


Figure 15. Capacitance vs Drain to Source Voltage

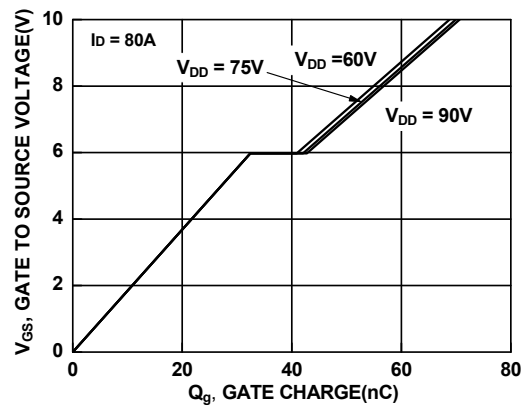



Figure 16. Gate Charge vs Gate to Source Voltage



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